

ABSTRACT OF THE DISCLOSURE

2 A microelectronic device fabricating method includes providing a
3 substrate having a beveled portion and forming a layer of structural
4 material on the beveled portion. Some of the structural material can
5 be removed from the beveled portion by anisotropic etching to form a
6 device feature from the structural material. The device feature can
7 be formed on the beveled portion as with a pair of spaced, adjacent
8 barrier material lines that are substantially void of residual shorting
9 stringers extending therebetween. Structural material can be removed
10 from the beveled portion to form an edge defined feature on a
11 substantially perpendicular edge of the substrate. The beveled portion
12 and perpendicular edge can be part of a mandril. The mandril can
13 be removed from the substrate after forming the edge defined feature.

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